3.0 A, Low Dropout Linear Regulator with Enhanced ESD Protection

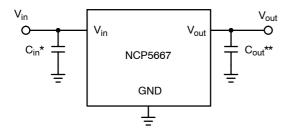
The NCP5667 is a high performance, low dropout linear regulator designed for high power applications that require up to 3.0 A current. A thermally robust, 3 pin D²PAK, combined with an architecture that offers low ground current (independent of load), provides for a superior high-current LDO solution.

Features

- ±1% Output Voltage Accuracy
- Ultra-Fast Transient Response (Settling Time: 1–3 μs)
- Enhanced ESD Ratings: 4 kV (HBM), 400 V (MM)
- Low Ground Current Independent of Load (3.0 mA Maximum)
- Current Limit Protection
- Thermal Protection
- Power Supply Rejection Ratio > 65 dB
- Stable with Aluminum, Tantalum and Ceramic Capacitors
- Functional Substitute for LM323
- This is a Pb-Free Device

Applications

- Servers
- DTV and Flat Panel Applications
- Post Regulation for Power Supplies
- Laptop Computing Applications
- USB Powered Applications
- Networking Equipment
- Gaming and STB Modules



* C_{in} – 4.7 μF to 220 μF recommended

**Cout – 2.2 μF to 220 μF recommended

See more details in the Application Information section

Figure 1. Typical Application Circuit



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MARKING

xx = Voltage Option 50 = 5.0 V

A = Assembly Location

WL = Wafer Lot Y = Year WW = Work Week G = Pb-Free

Tab = GND

Pin 1. V_{in} 2. GND

3. Vout

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

PIN FUNCTION DESCRIPTION

Pin No.	Pin Name	Description		
1	V _{in}	Positive Power Supply Input Voltage		
2, Tab	GND	Power Supply Ground		
3	V _{out}	Regulated Output Voltage		

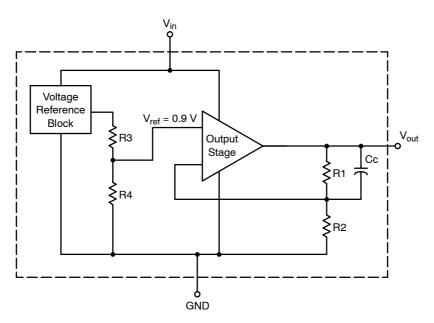


Figure 2. Block Diagram

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage (Note 1)	V _{in}	18	Vdc
Output Pin Voltage	V _{out}	-0.3 to (V _{in} + 0.3)	V
Maximum Junction Temperature	T _{J(max)}	150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Moisture Sensitivity Level	MSL	1	-
ESD Capability, Human Body Model (Note 2)	ESD _{HBM}	4000	V
ESD Capability, Machine Model (Note 2)	ESD _{MM}	400	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Characteristics (Note 1) Thermal Resistance Junction-to-Ambient (Note 3) Thermal Resistance Junction-to-Case	R _{θJA} R _{θJC}	45 5.0	°C/W

OPERATING RANGES

Rating	Symbol	Value	Unit
Operating Input Voltage (Note 1)	V _{in}	(V _{out} + V _{DO}) to 9	V
Operating Ambient Temperature Range	T _A	-40 to +85	°C

^{1.} Refer to Electrical Characteristics and Application Information for Safe Operating Area.

This device series contains ESD protection and exceeds the following tests: Human Body Model (HBM) JESD 22-A114-B Machine Model (MM) JESD 22-A115-A.

^{3.} As measured using a copper heat spreading area of 650 mm 2 , 1 oz copper thickness.

ELECTRICAL CHARACTERISTICS ($V_{in} = V_{out(nom)} + 1.5 \text{ V}$, for typical values $T_A = 25^{\circ}\text{C}$, for min/max values $T_A = -40^{\circ}\text{C}$ to 85°C , $C_{in} = 1.5 \text{ V}$, for typical values $T_A = 25^{\circ}\text{C}$, for min/max values $T_A = -40^{\circ}\text{C}$ to 85°C , $C_{in} = 1.5 \text{ V}$, for typical values $T_A = 25^{\circ}\text{C}$, for min/max values $T_A = -40^{\circ}\text{C}$ to 85°C , $T_{in} = 1.5 \text{ V}$, for typical values $T_{in} =$ = 100 μ F, C_{out} = 33 μ F, unless otherwise noted. (Note 4))

Characteristic	Symbol	Min	Тур	Max	Unit
Output Voltage (Note 6)	V _{out}				V
$ \begin{array}{l} 5.0 \text{ V Regulator} \\ T_{A} = 25^{\circ}\text{C (V}_{in} = 6.5 \text{ V to 7.0 V, I}_{out} = 10 \text{ mA to 3.0 A)} \\ T_{A} = -20 \text{ to } +125^{\circ}\text{C (V}_{in} = 6.5 \text{ V to 7.0 V, I}_{out} = 10 \text{ mA to 3.0 A)} \\ T_{A} = -40 \text{ to } +150^{\circ}\text{C (V}_{in} = 6.5 \text{ V to 7.0 V, I}_{out} = 10 \text{ mA to 3.0 A)} \\ \end{array} $		4.950 (-1%) 4.925 (-1.5%) 4.900 (-2%)	5.000 5.000 5.000	5.050 (+1%) 5.075 (+1.5%) 5.100 (+2%)	
Line Regulation (I _{out} = 10 mA, V _{out} +1.5 V < V _{in} < 7.0 V) (Note 5)	REG _{line}	-	0.03	-	%
Load Regulation (10 mA < I _{out} < 3.0 A) (Note 5)	REG _{load}	-	0.2	-	%
Dropout Voltage (I _{out} = 3.0 A)	V_{DO}	-	1.0	1.3	V
Peak Output Current Limit	l _{out}	3.0	-	-	Α
Internal Current Limitation (Note 5)	I _{lim}	-	4.5	-	Α
Ripple Rejection (120 Hz) (Note 5) Ripple Rejection (1 kHz) (Note 5)	RR	- -	70 65	- -	dB
Output Noise Voltage (I_{out} = 10 mA, C_{out} = 1.0 μ F, f = 10 Hz to 100 kHz) (Note 5)	V _n	-	105	-	μV_{rms}
Thermal Shutdown (Note 5)	T _{SHD}	-	160	-	°C
Ground Current (I _{out} = 3.0 A)	I _{GND}	_	2.4	3.0	mA

Performance guaranteed over specified operating conditions by design, guard banded test limits, and/or characterization, production tested at T_J = T_A = 25°C. Low duty cycle pulse techniques are used during testing to maintain the junction temperature as close to ambient as possible.
 Typical values are based on design and/or characterization.
 Other fixed output voltages available at 0.9 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.0 V, 3.3 V per request.

TYPICAL CHARACTERISTICS

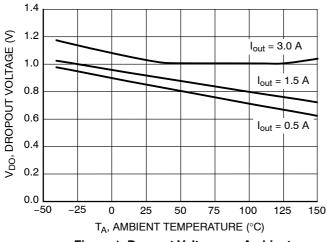


Figure 1. Dropout Voltage vs. Ambient Temperature

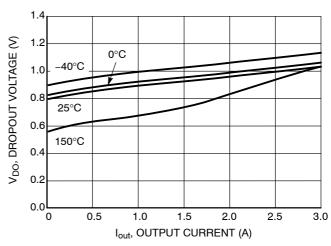


Figure 2. Dropout Voltage vs. Output Current

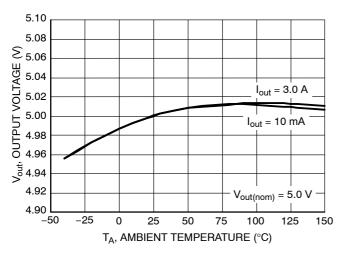


Figure 3. Output Voltage vs. Ambient Temperature

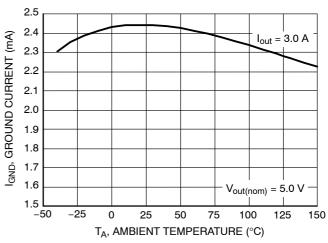


Figure 4. Ground Current vs. Ambient Temperature

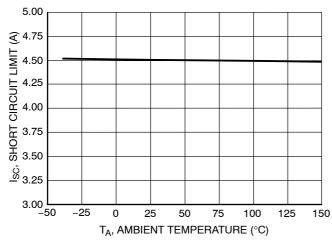


Figure 5. Short Circuit Current Limit vs. Ambient Temperature

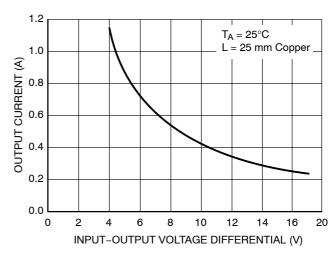


Figure 6. Output Current vs. Input-Output Voltage Differential

TYPICAL CHARACTERISTICS

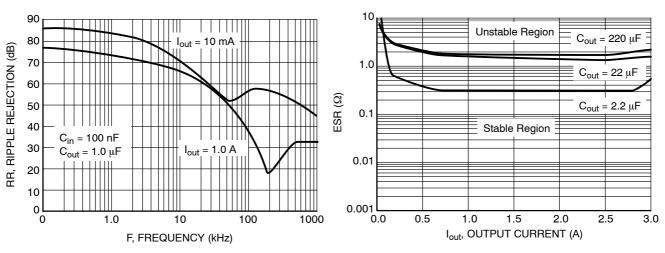
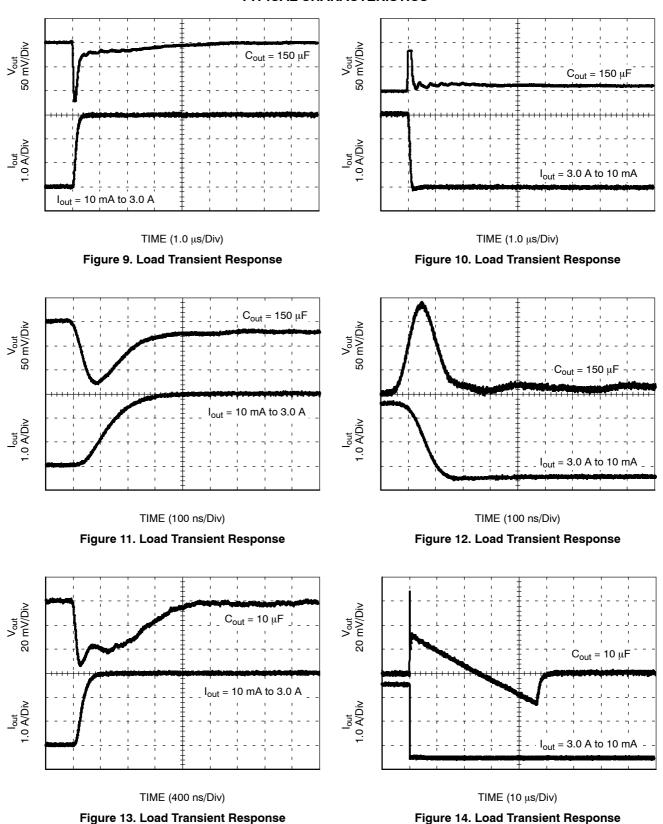


Figure 7. Ripple Rejection vs. Frequency

Figure 8. Output Capacitor ESR Stability vs.
Output Current

TYPICAL CHARACTERISTICS



NOTE: Typical characteristics were measured with the same conditions as electrical characteristics, unless otherwise noted.

APPLICATION INFORMATION

The NCP5667 is a high performance low dropout 3.0 A linear regulator suitable for high power applications. It is thermally robust and includes the safety features necessary during a fault condition, which provide for an attractive high current LDO solution for server, ASIC power supplies, networking equipment applications, and many others.

Input Capacitor

An input bypass capacitor is recommended to improve transient response or if the regulator is located more than a few inches from the power source. This will reduce the circuit's sensitivity to the input line impedance at high frequencies and significantly enhance the output transient response. Different types and different sizes of input capacitors can be chosen dependent on the quality of power supply. The range of 4.7 μF to 220 μF should cover most of the applications. The higher the capacitance, the lower change of input voltage due to line and load transients. The bypass capacitor should be mounted with shortest possible lead or track length directly across the regulator's input terminals.

Output Capacitor

The output capacitor is required for stability. The NCP5667 remains stable with ceramic, tantalum, and aluminum electrolytic capacitors with a minimum value of 2.2 μF . See Figure 8 for stable region of ESR for various output capacitors. The range of 2.2 μF to 220 μF should cover most of the applications. The higher the capacitance, the better load transient response. When a high value capacitor is used, a low value capacitor is also recommended to be put in parallel. The output capacitors should be placed as close as possible to the output pin of the device. This should help ensure ultrafast transient response times.

Current Limit Operation

As the peak output current increases beyond its limitation, the device is internally clampled to 4.5 A, thus causing the output voltage to decrease and go out of regulation. This allows the device never to exceed the maximum power dissipation.

Input Voltage Operating Range

The NCP5667 is guaranteed to protect itself from self destruction due to excessive power dissipation by activating current limit and thermal shutdown protections. These destructive situations can happen during very fast startup with large output capacitors or when output is short circuited. As long as the input voltage is lower than maximum operating voltage (9 V), the maximum power dissipation is never exceeded.

If input voltage is between maximum operating voltage (9 V) and absolute maximum voltage (18 V) power dissipation must never exceed limits specified in Thermal Consideration section for safety operation.

To use the device over maximum operating voltage the slow startup, not large output capacitors and no short circuit is recommended to maintain.

Thermal Consideration

The maximum device power dissipation can be calculated by:

$$P_{D} = \frac{T_{J(max)} - T_{A}}{R_{\theta JA}}$$

The bipolar process employed for this IC is fully characterized and rated for reliable 18 V operation. To avoid damaging the part or degrading it's reliability, power dissipation transients should be limited to 30 W for D²PAK. For open–circuit to short–circuit transient,

PDTransient = Vin(operating max) * ISC

ORDERING INFORMATION

Device	Nominal Output Voltage	Package	Shipping†	
NCP5667DS50R4G (Note 7)	5.0 V	D ² PAK (Pb-Free)	800 / Tape & Reel	

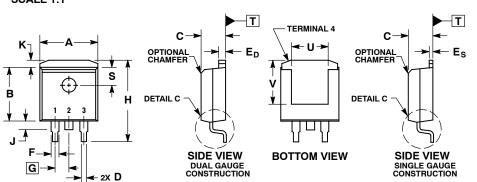
^{7.} Other fixed output voltages available at 0.9 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.0 V, 3.3 V per request.

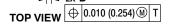
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

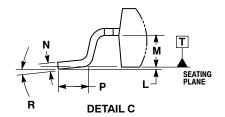


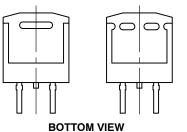
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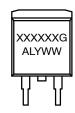


OPTIONAL CONSTRUCTIONS

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCHES. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS
- A AND K.
 DIMENSIONS U AND V ESTABLISH A MINIMUM
- MOUNTING SURFACE FOR TERMINAL 4.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.
- SINGLE GAUGE DESIGN WILL BE SHIPPED AF-TER FPCN EXPIRATION IN OCTOBER 2011.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.386	0.403	9.804	10.236	
В	0.356	0.368	9.042	9.347	
С	0.170	0.180	4.318	4.572	
D	0.026	0.036	0.660	0.914	
ED	0.045	0.055	1.143	1.397	
Es	0.018	0.026	0.457	0.660	
F	0.051	REF	1.295 REF		
G	0.100 BSC		2.540 BSC		
Н	0.539	0.579	13.691 14.707		
J	0.125	MAX	3.175 MAX		
K	0.050	REF	1.270 REF		
L	0.000	0.010	0.000	0.254	
M	0.088	0.102	2.235	2.591	
N	0.018	0.026	0.457	0.660	
P	0.058	0.078	1.473	1.981	
R	0°	8°	0°	8°	
S	0.116 REF		2.946	REF	
U	0.200 MIN		5.080 MIN		
V	0.250 MIN		6.350) MIN	

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Assembly Location

= Wafer Lot 1 Υ = Year ww = Work Week G = Pb-Free Package

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16.155		. ———	- 8.380
16.155			2X 3.504

SOLDERING FOOTPRINT*

← 10.490 →

	ļ [2X 3.504
2X	(1.016 →		Ī	<u> </u>
		5.080 PITCH	DIME	NSIONS: MILLI

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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